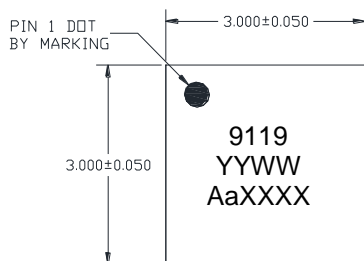
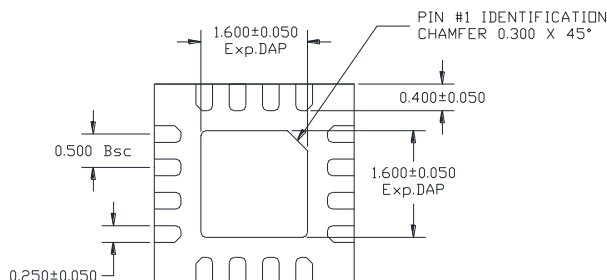


Package Marking and Dimensions

Marking: Part number – 9119
Date - YYWW
Lot code – AaXXXX

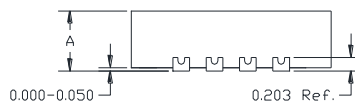


TOP VIEW



BOTTOM VIEW

A		TSLP
	MAX.	0.900
	NOM.	0.850
	MIN.	0.800

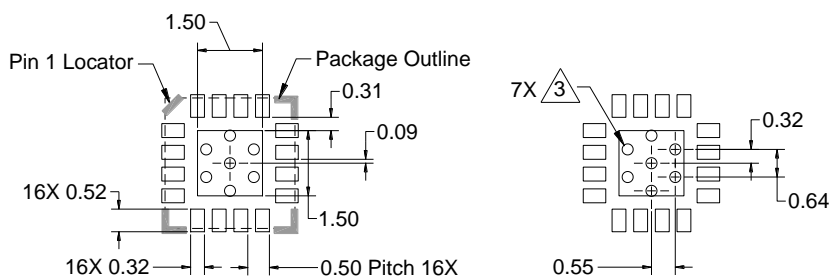


TOP VIEW

Notes:

1. All dimensions are in millimeters. Angles are in degrees.
2. The terminal #1 identifier and terminal numbering conform to JESD 95-1 SPP-012.
3. Contact plating: NiPdAu

PCB Mounting Pattern



COMPONENT SIDE

NOTES:

1. All dimensions are in millimeters. Angles are in degrees.
2. Use 1 oz. copper minimum for top and bottom layer metal.
3. Vias are required under the backside paddle of this device for proper RF/DC grounding and thermal dissipation. We recommend a 0.35mm (#80/.0135") diameter bit for drilling via holes and a final plated thru diameter of 0.25 mm (0.10").
4. Ensure good package backside paddle solder attach for reliable operation and best electrical performance.